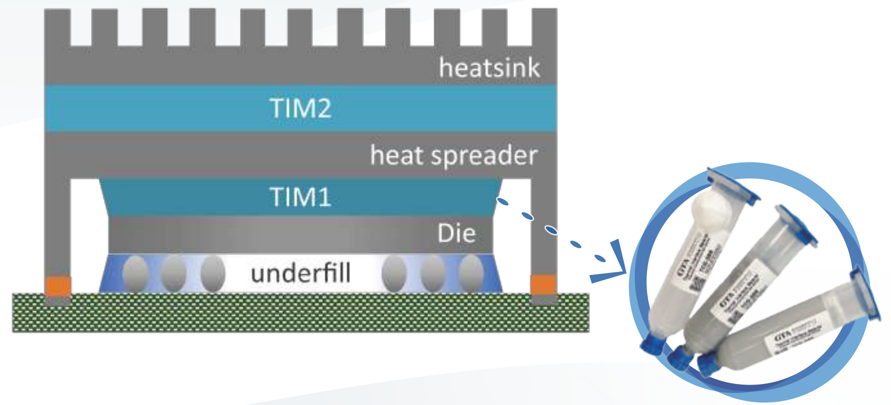
GTA
Material Co.,Ltd.

導熱膏 (TIM 1)
Thermal interface material

特性 / Features

- 熱固型材料
- 適當的硬度及延伸性
- 耐溫及低孔隙發生率



應用於覆晶封裝中晶片和蓋板間的熱介面材料(以下稱TIM1)，可填充在晶片與蓋板間的空隙，此熱介面材料經由加熱方式固化後，具適當的硬度及延伸性，在高溫環境不發生介面分離、低空隙發生率、高導熱性、低熱阻係數等特性。它可廣泛應用於高速元件，例如中央處理器、記憶體、網路微處理器等高階產品。

規格 / Specification

產品名稱		TCG-388	TCG-488	TCG-588
顏色		灰	灰	灰
熱導率 (W/m・K)		4.0	5.2	6.1
熱阻值 (°Cxcm^2/W)		0.05	0.07	0.06
黏接線厚度(μm)		38	50	55
比重@25°C		2.15	2.20	2.21
揮發率@150°C/24h(%)		0.05	0.07	0.07
固化後	硬度 shore OO	46	55	68
	延伸%	40	30	25

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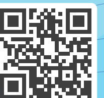

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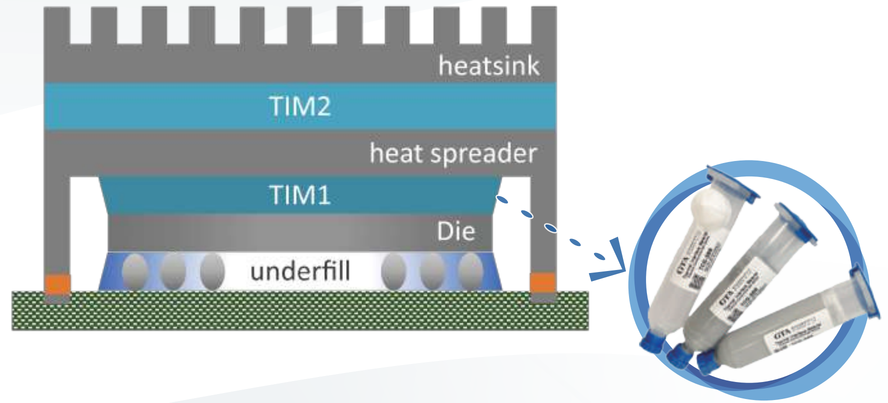

Features

- Thermal cured material
- Appropriate hardness and elongation characteristics
- No delamination and low void at high temperature

The thermal interface material (TIM1) is utilized to fill the gap between Si-chip and lid in "Flip Chip" packaging. The thermal cured TIM1 exhibits appropriate hardness and elongation characteristics, leading to low void and no delamination at high temperatures. Besides, The thermal cured TIM1 shows high thermal conductivity and low thermal resistance. It can be wildly used in CPU, memory and microprocessors.

Specification

Product Name		TCG-388	TCG-488	TCG-588
Color		Grey	Grey	Grey
Thermal conductivity (W/m·K)		4.0	5.2	6.1
Thermal resistance (°Cxcm^2/W)		0.05	0.07	0.06
Bond line thickness (μm)		38	50	55
Specific gravity@25°C		2.15	2.20	2.21
Volatile content@150°C/24h(%)		0.05	0.07	0.07
Thermal cured	hardness shore OO	46	55	68
	elongation %	40	30	25

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